

HT5010 TECHNOLOGY PACKAGE

Honeywell

Rev. 1

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Thermal Conductive Gel HT5010

OVERVIEW

Honeywell HT5010, is a soft, single part, dispensable thermal gap filler with a high thermal conductivity. Based on a novel polymer system, this material exhibits excellent reliability. A proprietary filler material combination provides high thermal conductivity of 5.0 W/m·K suitable for high

A proprietary filler material combination provides high thermal conductivity of 5.0 W/m ·K suitable for high performance devices.

BENEFITS AND FEATURES

- Low contact resistance
- Easy to dispense and rework
- High compressibility for low stress applications
- Long-term reliability
- Less oil separation
- · Less pump out and cracking

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Memory & Power Modules

Storage & Use

Shelf Life 6 months at 23±2°C

Honeywell

Basic Properties

Property	HT5010
Thermal Conductivity (W/m·K)	5.2
@ 1mm TH	5.2
Dispense Rate (g/min)	
30cc EFD syringe with no tip attachment, 0.100' orifice @0.6MPa pressure	>14
BLT (mm)	0.14
Color	Grey



Outgassing

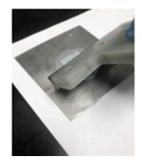
Out gassing



125°C Baking

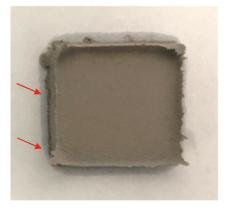


Oil bleeding



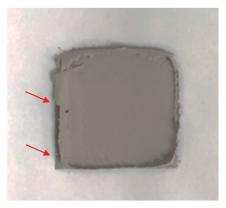
Sample size: 25.4X25.4X1.5mm Pasted on A4 paper

Oil bleeding (RT)



After 1 day

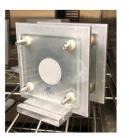
Oil bleeding (80° C)



After 1 day

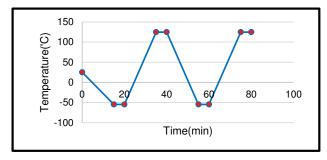
Dripping & Cracking





TC chamber

Vertical Position

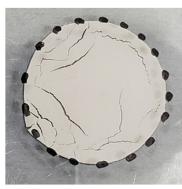


- Ramp time: 15mins
- Dwelling time @-55°C and 125°C:5mins
- Every cycle: 40mins

2 mm Gap

0.3 mm Gap





After 3wks

Compressibility



Test Condition
ASTM D575
Speed: 0.6 mm/s
Sample thickness: 1mm
Contact Area: 1 in.^2

HT5010 Compression-Deflection

